



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-11-30
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana San Biagio	<b>Representative Title</b>	AMG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HYWY*V631BRL	A	ZS1A	2016-11-30
Amount	UoM	Unit type	ST ECOPACK Grade	
16.38	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
tin is used or other bulk terminati	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	2.9x1.6x1.05	5	gull wing	
Comment	Package: WY SOT 23-5; MDF valid for TSV6311LT and TSV631A1LT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HYWY*V631BRL					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.411	mg	supplier	die	Silicon (Si)	7440-21-3		0.398	mg	968370	24298
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	9732	244
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	2433	61
Leadframe	Copper & its alloys	6.860	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.008	mg	19465	488
				supplier	alloy	Copper (Cu)	7440-50-8		6.590	mg	960641	402320
				supplier	alloy	Iron (Fe)	7439-89-6		0.165	mg	24052	10073
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.002	mg	292	122
				supplier	alloy	Zinc (Zn)	7440-66-6		0.009	mg	1312	549
				supplier	metallization	Nickel (Ni)	7440-02-0		0.086	mg	12536	5250
	Precious metals			supplier	metallization	Palladium (Pd)	7440-05-3		0.007	mg	1020	427
	Precious metals			supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	146	61
Die attach	Other Organic Materials	0.078	mg	supplier	glue	Silver (Ag)	7440-22-4		0.056	mg	717949	3419
				supplier	glue	methylene diacrylate	42594-17-2		0.013	mg	166667	794
				supplier	glue	Dicyclopentenloxyethyl methacrylate	68586-19-6		0.003	mg	38462	183
				supplier	glue	Bismaleimide resin	Proprietary		0.003	mg	38462	183
				supplier	glue	Palladium (Pd)	7440-05-3		0.001	mg	12821	61
				supplier	glue	Dicumyl peroxide	80-43-3		0.002	mg	25641	122
Bonding wires	Precious metals	0.155	mg	supplier	wire	Gold (Au)	7440-57-5		0.155	mg	1000000	9463
Encapsulation	Other Organic Materials	8.874	mg	supplier	Proprietary	Epoxy Resin	Proprietary		0.351	mg	39554	21429
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.132	mg	14875	8059
				supplier	mold compound	Phenol resin	Proprietary		0.367	mg	41357	22405
				supplier	mold compound	Silica	60676-86-0		7.113	mg	801555	434249
				supplier	mold compound	Carbon Black	1333-86-4		0.017	mg	1916	1038
				supplier	mold compound	Zinc hydroxide	20427-58-1		0.163	mg	18368	9951
				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.731	mg	82375	44628